



# Thermabond® Adhesives

## Thermally Conductive Adhesives For High Reliability

### Bond Reliability

Bonds securely to many substrate types, shapes, or textures

### Hot Spot Elimination

Thermal conductivity up to 3W/mK to transport heat away from hot spots

### Thermal-Mechanical Stress Decoupling

Low modulus and high shear strength prevent adhesive delamination

### Low Temperature Cure Cycle

Thermabond cure parameters can be as low as 100°C at 100 kPa, so surface mount components can be mounted on the PCB prior to bonding

### Uniform Bond Line Thickness

Precision calendering produces a uniform adhesive film

### Proven Performance

ARLON® Thermabond® adhesive products are the gold standard for critical, demanding electronic system applications

Properties	A9 Thermabond*	A5 Thermabond	A3 Thermabond	Supported Thermabond	Primerless E35 Thermabond	Low Outgassing Thermabond	Primerless Thermabond	Original Thermabond
Part Number**	99A90X008	99A50X008	99A30X008	48991A010	99950N008	99000W008	99990A008	99510N008
Tc (W/m-K) @ 100°C	3.0	1.4	1.0	0.4	2.5	1.5	0.4	0.4
Thermal Resistance	6.0E-05	9.6E-05	2.1E-04	7.1E-04	8.4E-05	4.2E-04	5.2E-04	5.7E-04
Shear Modulus (psi)	265	145	30	50	54	65	75	100
Lap Shear Strength (psi)	140	500	290	710	495	185	1000	600
Bonds Without Primer	Yes	Yes	Yes	Yes	Yes	No	Yes	No
Bond/Cure	Platen Press	Vacuum or Platen	Vacuum or Platen	Vacuum or Platen	Vacuum or Platen	Platen Press	Vacuum or Platen	Vacuum or Platen
Electrical	Insulative	Insulative	Insulative	Insulative	Conductive	Insulative	Insulative	Insulative
Thickness Range	.004" & up	.004" & up	.004" & up	.008" & up	.004" & up	.004" & up	.004" & up	.004" & up
Fiberglass Reinforcement	No	No	No	Yes	No	No	No	No

\* Patent Pending

\*\* Part Number Example: 99A90X### (### = 008 = .008" Thickness)